

CMV2000 and CMV4000

Soldering procedure

Manual Soldering

Use partial heating method and use a soldering iron with temperature control. The soldering iron tip temperature is not to exceed 350°C with 270°C maximum pin temperature, 2 seconds maximum duration per pin. Avoid global heating of the ceramic package during soldering. Failure to do so may alter device performance and reliability.

Flow soldering

Flow soldering is possible but not recommended. Solder dipping can cause damage to the glass and harm the imaging capability of the device. The figure below shows the maximum recommended thermal profile for a reflow soldering system. If the temperature/time profile exceeds these recommendations, damage to the image sensor can occur.

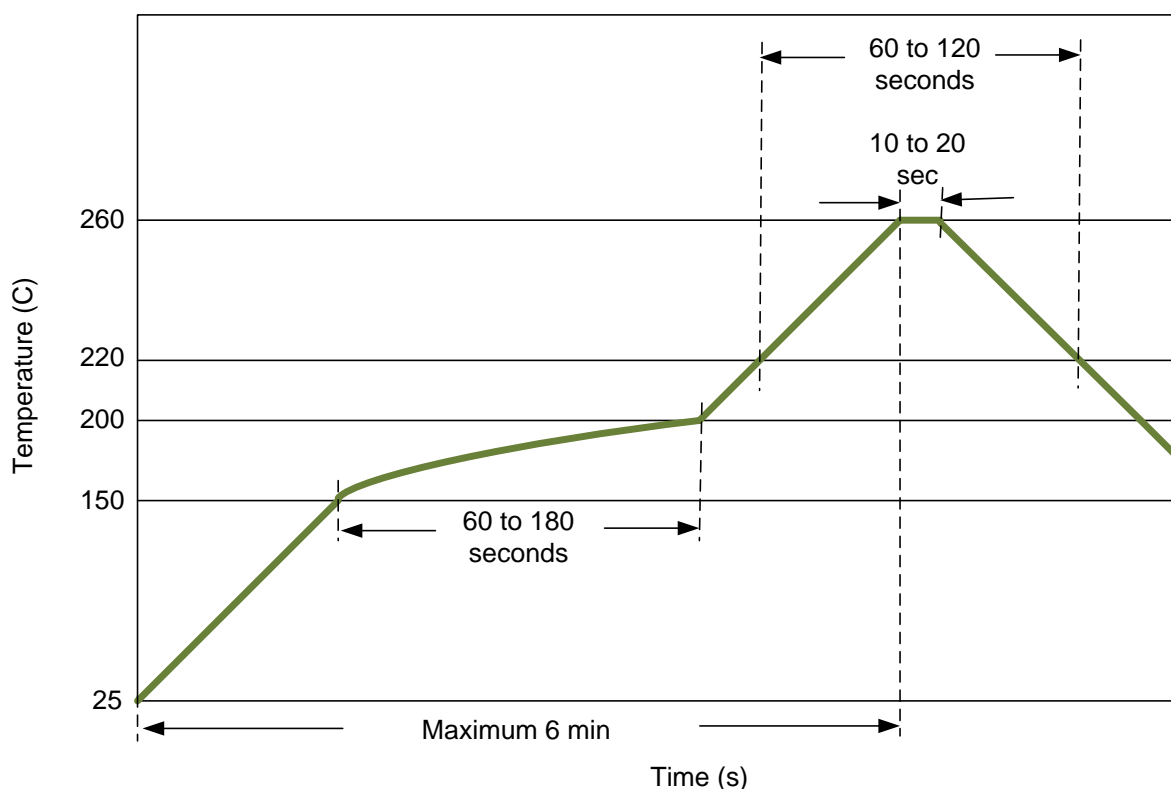


Image sensors with filter arrays (CFA) and micro-lens are especially sensitive to high temperatures. Prolonged heating at elevated temperatures may result in deterioration of the performance of the sensor. Best solution will be flow soldering or manual soldering of a socket (through hole or BGA) and plug in the sensor at latest stage of the assembly/test process. BGA solution allows more flexibility to the routing of the camera PCB.